L Number	Hits	Search Text	DB	Time stamp
1	3	(semiconductor adj substrate) and (glass	USPAT;	2004/10/18 09:06
		adj substrate) and ((conductive adj plug)	US-PGPUB;	
•		with insulat\$)	EPO; JPO;	
			DERWENT;	
3	18	((conductive adj plug) with insulat\$) and	IBM_TDB USPAT;	2004/10/18 09:11
	10	((conductive ad) ping) with insuracy) and imaging	US-PGPUB;	2004/10/10 09.11
		1	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	1	((conductive adj plug) with insulat\$) and	USPAT;	2004/10/18 09:11
		imager	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
5	77	((conductive adj plug) with insulat\$) and	USPAT;	2004/10/18 09:17
		optical	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
6	19	(/aandustiss add slus) with suide) and	IBM_TDB USPAT;	2004/10/10 00:17
١	19	((conductive adj plug) with oxide) and optical	USPAT; US-PGPUB;	2004/10/18 09:17
			EPO; JPO;	
			DERWENT;	
<u> </u>			IBM_TDB	
7	6	((conductive adj plug) with oxide) and	USPAT;	2004/10/18 09:18
		imaging	US-PGPUB;	
		,	EPO; JPO; DERWENT;	
			IBM TDB	
8	2	((conductive adj plug) with oxide) and	USPAT;	2004/10/18 09:18
		imager	US-PGPUB;	,
			EPO; JPO;	
		<u>,</u>	DERWENT;	
9	152	((conductive adj material) with oxide) and	IBM_TDB USPAT;	2004/10/18 09:19
	. 102	imager	US-PGPUB;	2004/10/10 05.15
			EPO; JPO;	
		•	DERWENT;	
10	0	//	IBM_TDB	0004/10/10 00 10
10	0	((conductive adj material) with oxide with (through adj hole)) and imager	USPAT; US-PGPUB;	2004/10/18 09:19
		(through adj hore), and imager	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
11	0	((conductive adj material) with oxide with	USPAT;	2004/10/18 09:19
		(hole)) and imager	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
12	3	(USPĀT;	2004/10/18 09:20
		(via)) and imager	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
13	. 9	((conductive adj material) with oxide with	USPAT;	2004/10/18 09:20
		(via)) and imaging	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
14	30	//gondustive add material with swide 199	IBM_TDB	2004/10/10 00:51
7.4	30	((conductive adj material) with oxide with (via)) and optical	USPAT; US-PGPUB;	2004/10/18 09:51
		(via), and operedi	EPO; JPO;	
		*	DERWENT;	
			IBM_TDB	
16 .	10	' ' ' ' ' ' ' ' ' '	USPAT;	2004/10/18 09:54
		plate)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
		L		

17	26	(imaging adj device) and (reinforce\$ near	USPAT;	2004/10/18 09:58
		(layer or film))	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
19	15	 (imaging adj device) with reinforce\$	USPAT;	2004/10/18 09:58
1 - 3		\limaging adj device, with lemiology	US-PGPUB;	2004/10/10 03:30
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	6	(solid adj state adj imaging adj device)	USPAT;	2004/09/28 10:07
		and translucent and (through adj hole) and	US-PGPUB;	
		terminal	EPO; JPO;	
			DERWENT;	
0.			IBM_TDB	
-	17	1=	USPAT;	2004/09/24 13:13
		(through adj hole) and terminal	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	100	/	IBM_TDB	0004/00/04 13:00
-	106	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2004/09/24 13:20
		(via) and terminal	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	59	(imaging adj device) and translucent and	USPAT;	2004/09/27 19:30
		(hole) and terminal	US-PGPUB;	2003/03/21 13.30
		(EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	6	(solid adj state adj imaging adj device)	USPAT;	2004/09/28 10:06
		and translucent and (semiconductor adj	US-PGPUB;	
		substrate)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	725	(solid adj state adj imaging adj device)	USPAT;	2004/09/24 13:25
		and (semiconductor adj substrate)	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	18	(solid adj state adj imaging adj device)	USPAT;	2004/09/27 15:54
	.	and (semiconductor adj substrate) and	US-PGPUB;	2501/05/21 15.54
		(external adj terminal)	EPO; JPO;	
			DERWENT;	·
	.4.		IBM_TDB	
-	20		USPĀT;	2004/09/27 19:09
		and (semiconductor adj substrate) and	US-PGPUB;	ļ
		(glass adj substrate)	EPO; JPO;	
			DERWENT;	
	1		IBM_TDB	0004400405
-	92	, , = , =	USPAT;	2004/09/27 17:11
		adj substrate) and (glass adj substrate)	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	1	(imaging adj device) and ((hole or via or	USPAT;	2004/09/27 17:12
	1	plug) adj semiconductor adj substrate) and	USPAT; US-PGPUB;	2004/03/2/ 1/:12
		(glass adj substrate)	EPO; JPO;	, · · · · · · · · · · · · · · · · · · ·
		(3-22 44) 2402014460/	DERWENT;	
			IBM TDB	
_ ·	0	(imaging adj device) and ((hole or via or	USPĀT;	2004/09/27 17:13
		plug) adj semiconductor adj substrate) and	US-PGPUB;	
		(transparent adj substrate)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1	(imaging adj device) and ((hole or via or	USPAT;	2004/09/27 17:13
		plug) adj semiconductor adj substrate) and	US-PGPUB;	
		(translucent adj substrate)	EPO; JPO;	
			DERWENT;	
L			IBM TDB	

				
-	2	(USPAT;	2004/09/27 17:13
		plug) near (semiconductor adj substrate))	US-PGPUB;	
		and (translucent adj substrate)	EPO; JPO;	
İ			DERWENT;	
_	5	(imaging adj device) and ((hole or via or	USPAT;	2004/09/27 17:14
		plug) near (substrate)) and (translucent	US-PGPUB;	2004/03/27 17:14
		adj substrate)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	6	(imaging adj device) and ((hole or via or	USPAT;	2004/09/27 17:18
		plug) with (substrate)) and (translucent	US-PGPUB;	
		adj substrate)	EPO; JPO;	
			DERWENT;	
1	1		IBM_TDB	
-	295	257/89.ccls.	USPAT;	2004/09/27 17:37
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1,600	057/501-	IBM_TDB	0004/00/07 10 04
_	1600	257/59.ccls.	USPAT;	2004/09/27 18:04
			US-PGPUB;	
	1		EPO; JPO; DERWENT;	
			IBM TDB	
_	109	257/59.ccls. and (semiconductor adj	USPAT:	2004/09/27 17:39
		substrate) and (glass adj substrate)	US-PGPUB:	2003/03/21 11.39
		Table 1 and (grade ad) bubblished	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1498	257/72.ccls.	USPĀT;	2004/09/27 17:51
		,	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	121		USPAT;	2004/09/27 17:55
		substrate) and (glass adj substrate)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	595	257/434.ccls.	IBM TDB	2004/00/07 10 04
_] 393	237/434.0018.	USPAT; US-PGPUB;	2004/09/27 18:04
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	6	257/434.ccls. and (semiconductor adj	USPAT;	2004/09/27 18:06
		substrate) and (glass adj substrate)	US-PGPUB;	10.00
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	93	257/460.ccls.	USPAT;	2004/09/27 19:18
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	3	257/460 gglg and (gggl;	IBM_TDB	2004/00/07 10 25
_	3	, , ,	USPAT;	2004/09/27 18:06
		substrate) and (glass adj substrate)	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	465	257/462.ccls.	USPAT;	2004/09/27 18:08
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	257/462.ccls. and (semiconductor adj	USPĀT;	2004/09/27 18:41
		substrate) and (glass adj substrate)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	,
			IBM TDB	

-	1385	(semiconductor adj substrate) and (glass	USPAT;	2004/09/27 19:11
		adj substrate) and display and image	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	663	through adj hole adj formed adj substrate	<pre>IBM_TDB USPAT;</pre>	2004/09/28 06:37
-	003	through adj hore adj formed adj substrace	US-PGPUB;	2004/09/28 00.37
			EPO; JPO;	
			DERWENT;	
		,	IBM TDB	
-	45	through adj hole adj formed adj	USPĀT;	2004/09/27 19:12
		semiconductor adj substrate	US-PGPUB;	
			EPO; JPO;	
		•	DERWENT;	
	0.50	240/240	IBM_TDB	0004/00/07 10 10
_	250	348/340.ccls.	USPAT;	2004/09/27 19:18
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	O	translucent adj member adj formed adj	USPAT;	2004/09/27 19:31
	1	substrate	US-PGPUB;	
	!		EPO; JPO;	
	· .		DERWENT;	
			IBM_TDB	0004/00/00
-	1		USPAT;	2004/09/27 19:32
		substrate	US-PGPUB;	
		<i>,</i>	EPO; JPO;	
			DERWENT; IBM TDB	
_	268	transparent near (formed adj substrate)	USPAT;	2004/09/27 19:32
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;]`
			IBM_TDB	
-	5	translucent near (formed adj substrate)	USPAT;	2004/09/27 19:33
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
-	628	glass near (formed adj substrate)	USPAT;	2004/09/27 19:33
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	87		USPAT;	2004/09/28 06:57
		substrate) and (imager or imaging or	US-PGPUB;	
		display or photodiode)	EPO; JPO; DERWENT;	
		,	IBM TDB	
_	256	(hole adj formed adj substrate) and	USPAT;	2004/09/28 06:59
		(imager or imaging or display or	US-PGPUB;	
[photodiode)	EPO; JPO;	
-			DERWENT;	
			IBM_TDB	
-	162	438/75.ccls.	USPAT;	2004/09/28 07:04
			US-PGPUB;	
			EPO; JPO; DERWENT;	·
]			IBM TDB	
_	728	438/73.ccls.	USPAT;	2004/09/28 07:08
]			US-PGPUB;	, 55, 25 5, .00
]			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
[-	210		USPAT;	2004/09/28 07:21
		display or photodiode)	US-PGPUB;	
			EPO; JPO;	
[İ '	DERWENT;	
			IBM_TDB	

_	17	257/252.ccls. and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO;	2004/09/28 07:34
			DERWENT; IBM_TDB	
-	32	257/253.ccls. and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO;	2004/09/28 07:37
_	101	257/414.ccls. and (imager or imaging or	DERWENT; IBM_TDB USPAT;	2004/09/28 07:43
		display or photodiode)	US-PGPUB; EPO; JPO; DERWENT;	2004/03/20 07.43
_	1252	1	IBM_TDB USPAT; US-PGPUB;	2004/09/28 08:39
		substrate) and ((glass or transparent or translucent) adj substrate) and (imager or imaging or display or photodiode)	EPO; JPO; DERWENT; IBM TDB	
_	28	257/\$.ccls. and (semiconductor adj substrate) and ((glass or transparent or translucent) adj member) and (imager or	USPAT; US-PGPUB; EPO; JPO;	2004/09/28 08:46
	10	imaging or display or photodiode)	DERWENT; IBM_TDB	2004/00/20 00:50
	19	438/\$.ccls. and (semiconductor adj substrate) and ((glass or transparent or translucent) adj member) and (imager or imaging or display or photodiode)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/28 08:50
_	6		IBM_TDB USPAT; US-PGPUB;	2004/09/28 09:11
		translucent) adj member) and (imager or imaging or display or photodiode)	EPO; JPO; DERWENT; IBM TDB	
_	4	((glass or transparent or translucent) adj member) near (semiconductor adj substrate)	USPAT; US-PGPUB; EPO; JPO;	2004/09/28 09:13
_	560	((glass or transparent or translucent)	DERWENT; IBM_TDB USPAT;	2004/09/28 09:15
		near (semiconductor adj substrate)) and (imager or imaging or display or photodiode)	US-PGPUB; EPO; JPO; DERWENT;	
-	1039	(solid adj state adj imaging adj device) and (translucent or glass or transparent)	IBM_TDB USPAT; US-PGPUB;	2004/09/28 10:38
			EPO; JPO; DERWENT; IBM_TDB	
_	125	(solid adj state adj imaging adj device) and (quartz)	USPAT; US-PGPUB; EPO; JPO;	2004/09/28 10:39
-	0	351997.FREF.	DERWENT; IBM_TDB USPAT;	2004/09/30 08:55
			US-PGPUB; EPO; JPO; DERWENT; IBM TDB	
_	0	0351997.FREF.	USPAT; US-PGPUB; EPO; JPO;	2004/09/30 08:55
_	1	2001351997.FREF.	DERWENT; IBM_TDB USPAT;	2004/09/30 08:57
			US-PGPUB; EPO; JPO; DERWENT;	2007,007,00
		_	IBM TDB	

- 0 2001351997.FRPD. USPAT; US-PCPUB; EPO, JPO, DEMBENT; ISBUTCH DEMBENT;					
- 0 35197.FRPD. EPO, JPO, DEAWENT; ISM, TOB USPÄT; US-PGPUB, EPO, JPO, DEAWENT; US-PGPUB, EPO, JPO, JPO, DEAWENT; US-PGPUB, EPO, JPO, JPO,	-	0	2001351997.FRPD.		2004/09/30 08:56
- 0 351997.FRPD.				· ·	
18M TOB					
- 0 351997.FRPD. USPÄT: USPÄCHUR; EPO. JPO. DERMENT; IRM TIB USPÄT: USPÄCHUR; EPO. JPO. DERMENT; IRM TIB USPÄT: USPÄCHUR; EPO. JPO. DERMENT; IRM TIB USPÄT: USPÄCHUR; EPO. JPO. DERMENT; IRM TIB USPÄT: USPÄCHUR; EPO. JPO. DERMENT; IRM TIB USPÄT: USPÄCHUR; EPO. JPO. DERMENT; IRM TIB USPÄT: USPÄCHUR; EPO. JPO. DERMENT; IRM TIB USPÄT: USPÄCHUR; EPO. JPO. DERMENT; IRM TIB USPÄT; USPÄCHUR; EPO. JPO. DERMENT; EPO. JPO.					
	_	0	351997.FRPD.		2004/09/30 08:56
				US-PGPUB;	
1 173845.FREF. US-PGFUB; EPO; JPO; DERMENT; IND TOB USPAT; U					
- 1 173845.FREF. US-FGPUB; EPG; JPG; DERWENT; IBM_TDB US-FAT; US-FGPUB; EPG; JPG; JPG; DERWENT; IBM_TDB US-FAT; US-FGPUB; EPG; JPG; JPG; DERWENT; IBM_TDB US-FAT; US-FGPUB; EPG; JPG; DERWENT; IBM_TDB US-FAT; US-FGPUB; EPG; JPG; JPG; DERWENT; IBM_TDB US-FAT; US-FGPUB; EPG; JPG; JPG; DERWENT; IBM_TDB US-FAT; US-FGPUB; EPG; JPG; DERWENT; IBM_TDB US-FAT; US-FGPUB; EPG; JPG; JPG; DERWENT; IBM_TDB US-FAT; US-FGPUB; EPG; JPG; JPG; JPG; DERWENT; IBM_TDB US-FAT; US-FGPUB; EPG; JPG; JPG; JPG; JPG; JPG; JPG; JPG; J	,				
- 0 2000173845.FREF. US-PCPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PCPUB; EPC; JPC; JPC; DERWENT; IBM TDB USPAT; US-PCPUB; EPC; JPC; JPC; JPC; JPC; JPC; JPC; JPC; J	,	1	172045 EDEE		2004/00/20 00.57
- 0 2000173845.FREF.	-		1/3043.fREf.		2004/09/30 00:37
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- 1 173845.FRPN. US-PGPUB; PPO; JPO; DERWENT; IBM TOB USPAT; US-			·		
PRO; JPO; DERMENT; IEM TDB USPAT; US-PGPUB; EPO; JPO; DERMENNT;	-	0	2000173845.FREF.		2004/09/30 08:57
- 1 173845.FRPN.				1	
TIM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; U					
- 1 173845.FRPN. USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;					
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- 0 fumi-hat\$.in. DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; US-PGPUB; EPC; JPC; DERWENT; USPAT; US-PGPUB; EPC; JPC; DERWENT; USPAT; U					
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- 0 fumi-ha\$.in. DERWENT; IBM_TDB USPAT; US-PGPUB; EPG; JPG; DERWENT; IBM_TDB USPAT; US-PGPUB; EPG; JPG; DERWENT; IBM_TDB USPAT; US-PGPUB; EPG; JPG; DERWENT; IBM_TDB USPAT; US-PGPUB; EPG; JPG; DERWENT; IBM_TDB USPAT; US-PGPUB; EPG; JPG; DERWENT; IBM_TDB USPAT;			·	1	
- 0 fumi-ha\$.in. IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; USPĀT; US-PGPUB; EPO; JPO; DERWENT; USPĀT; US-PGPUB; EPO; JPO; DERWENT; USPĀT; US-PGPUB; EPO; JPO; DERWENT; USPĀT; US					,
- 0 fumi-ha\$.in.					
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT; EPO; JPO; DERWENT; EPO; JPO; DERWENT;	_	0	fumi_has in		2004/00/20 00.00
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- 0 fumi-h\$.in.					
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT;					
EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;	-	0	fumi-h\$.in.		2004/09/30 09:08
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;			·		
- 10 fumio-h\$.in. IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPAT					
- 10 fumio-h\$.in. USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT;					
US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENT;	_	10	fumio-h\$.in.		2004/09/30 09:09
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT;					
- 0 fumio-hata.in. IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; EP					
- 0 fumio-hata.in.					
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT;	1_	_ ^	fumio-bata in		2004/09/20 00-10
- 1 fumio-hat\$.in. EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT;	-		Tumio-naca.in.	•	2004/05/30 09:10
- 1 fumio-hat\$.in. fumio-hat\$					
fumio-hat\$.in. 1 fumio-hat\$.in. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;					
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;					
- 30 (reinforcement adj plate) and (glass adj substrate) 1 (reinforcement adj plate) and (solid adj state adj imaging adj device) EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	-	1	fumio-hat\$.in.		2004/09/30 09:10
- 30 (reinforcement adj plate) and (glass adj Substrate) 1 (reinforcement adj plate) and (solid adj State adj imaging adj device) DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;					
- 30 (reinforcement adj plate) and (glass adj substrate) IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPAT; USPAT; USPAT; USPAT; USPAT; USPAT; USPAT; USPAT; USPAT; USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT;					
- 30 (reinforcement adj plate) and (glass adj Substrate) 1 (reinforcement adj plate) and (solid adj State adj imaging adj device) 1 (reinforcement adj plate) and (solid adj State adj imaging adj device) 2004/10/16 18:03 2004/10/16 18:03 2004/10/16 18:04 2004/10/16 18:04					
substrate) US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; US-PGPUB; EPO; JPO; DERWENT; State adj imaging adj device) US-PGPUB; EPO; JPO; DERWENT;	-	30	(reinforcement adj plate) and (glass adj	USPAT;	2004/10/16 18:03
- 1 (reinforcement adj plate) and (solid adj USPAT; US-PGPUB; EPO; JPO; DERWENT;				US-PGPUB;	
- 1 (reinforcement adj plate) and (solid adj USPAT; US-PGPUB; EPO; JPO; DERWENT;					
- 1 (reinforcement adj plate) and (solid adj USPĀT; US-PGPUB; EPO; JPO; DERWENT;					
state adj imaging adj device) US-PGPUB; EPO; JPO; DERWENT;	_	1	(reinforcement add plate) and (colid add		2004/10/16 10:04
EPO; JPO; DERWENT;	-				2004/10/10 18:04
DERWENT;					
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				IBM_TDB	

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-	5	(reinforcement adj plate) and (imaging adj	USPAT;	2004/10/16 18:11
		device)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	57	(sio or (silicon adj oxide)) and (imaging	USPAT;	2004/10/16 18:37
		adj device) and (through adj hole)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	161	(sio or (silicon adj oxide)) and (optical	USPĀT;	2004/10/16 18:38
[adj element) and (through adj hole)	US-PGPUB;	=====
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	49	((sio or (silicon adj oxide)) with via)	USPAT;	2004/10/16 18:34
	3.5	and (optical adj element)	US-PGPUB;	2004/10/10 10.54
		and (optical ad) element)	EPO; JPO;	
			DERWENT;	
	35	//sis on /silinon add suids)\ths	IBM_TDB	2004/10/16 10:24
-	33	(USPAT;	2004/10/16 18:34
		and (imaging adj device)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	55	((g-::)	USPAT;	2004/10/16 18:38
		adj device) and (through adj hole) and	US-PGPUB;	
		thickness	EPO; JPO;	
			DERWENT;	
			IBM_TDB	1
	23	((sio or (silicon adj oxide)) with	USPAT;	2004/10/16 18:38
		thickness) and (optical adj element) and	US-PGPUB;	
		(through adj hole)	EPO; JPO;	
			DERWENT;	
			IBM TDB	